

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	4121	metal with substrate same ground and conductive	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2005/07/25 14:21
L2	942	metal with substrate same ground with conductive	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2005/07/25 14:21
L3	576	metal with substrate with ground with conductive	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2005/07/25 14:42
L4	17	metal with substrate with ground with conductive and bridge with circuit	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2005/07/25 14:22
L5	190	metal with substrate with ground with conductive and integrated adj circuit	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2005/07/25 14:42

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	8	hybrid with metal with substrate and metal with substrate with insulating and (semiconductor or chip) same contact with substrate	USPAT; USOCR; EPO; JPO	OR	ON	2005/06/25 15:16
L2	3516	metal with substrate and metal with substrate with insulating and (semiconductor or chip) same contact with substrate	USPAT; USOCR; EPO; JPO	OR	ON	2005/06/25 15:16
L3	2962	metal with substrate and metal with substrate with insulating and (semiconductor or chip) with contact with substrate	USPAT; USOCR; EPO; JPO	OR	ON	2005/06/25 15:17
L4	1848	metal with substrate and metal with substrate with insulating and (semiconductor or chip) with contact with metal with substrate	USPAT; USOCR; EPO; JPO	OR	ON	2005/06/25 15:26
L5	234	metal with substrate and metal with substrate with insulating and (semiconductor or chip) with contact with metal with substrate and conductive with pattern	USPAT; USOCR; EPO; JPO	OR	ON	2005/06/25 15:24
L6	84	metal with substrate and metal with substrate with insulating and (semiconductor or chip) with contact with metal with substrate and conductive with pattern and capacitor	USPAT; USOCR; EPO; JPO	OR	ON	2005/06/25 15:25
L7	5	metal adj substrate and metal with substrate with insulating and (semiconductor or chip) with contact with metal with substrate and conductive with pattern and capacitor	USPAT; USOCR; EPO; JPO	OR	ON	2005/06/25 15:25
L8	71	metal adj substrate and metal with substrate with insulating and (semiconductor or chip) with contact with metal with substrate	USPAT; USOCR; EPO; JPO	OR	ON	2005/06/25 15:26